



MASK TECHNOLOGY PRODUCT CAPABILITY MATRIX

Mask Type	Max Trace Height	Minimum Solder Dam	*Tenting	Aspect Ratio	IPC SM-840C		
			Max Hole Diameter		Class III (Equiv to Class H)	U.L.#	
DUPONT							
8130 Vacrel E67095 (R)	5 mil	6 mil	40 mil	Unlimited	Yes		
8140 Vacrel E67095 (R)	6 mil	6 mil	40 mil	Unlimited	Yes		
Pyralux PC 1025	2.5 mil	6 mil	30 mil	Unlimited	Yes	Not Rated	
MORION							
KM 3 mil E68935 (S)	4 mil	5 mil	36 mil	Unlimited	Yes		
KM 4 mil E68935 (S)	5 mil	6 mil	36 mil	Unlimited	Yes		
Conformask 2523 ** E68935 (S)	4 mil	4 mil	25 mil	Unlimited	Yes		
5030 Series ** E68935 (S)	* 5 mil	6 mil	36 mil	Unlimited	Yes		
5040 Series ** E68935 (S)	* 6 mil	6 mil	40 mil	Unlimited	Yes		
LIQUID PHOTOIMAGEABLE SOLDER MASKS							
Taiyo PSR 4000 E69262	3.5 mil	3 mil	None	N/A	Yes		
Taiyo AUS5 (CSPs) E69262	3.5 mil	3 mil	None	N/A	Jedec	Level 3	
Taiyo PSR 9000 (Flex)	3 mil	5 mil	None	N/A	Yes	Not Rated	
Enthone DSR3241 AG E76244 (M)	3.5 mil		3 mil	None	N/A	Yes	
Enthone DSR3300G	3.5 mil	3 mil	None	N/A	Yes	E76244	
Morton *** Epic SP200 E68935 (S)	3.5 mil	3 mil	None	N/A	Yes		

Probimer 77	3.5 mil	3 mil	None	N/A	Yes	E191939
Shipley *** Ronacoat 5900	3.5 mil	3 mil	None	N/A	Yes	E80180

* The ability to cover high circuits and tent vias varies with circuit geometry, location, circuit density and side wall profile. Higher density areas are more easily covered and tented, whereas lower density areas are more difficult. Over etch and step plating also contribute to break-through (the so-called cookie cutter effect).

** Conformask 2523 is recommended to “cap” or “tent” vias for BGA applications.

*** Material available upon request.